



100V +175°C N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

| BV _{DSS} | R _{DS(ON)} Max | I _D Max T _C = +25°C | |
|-------------------|--------------------------------|--|--|
| 100V | 4.9mΩ @ V _G S = 10V | 115A | |

Description

This new generation N-Channel Enhancement Mode MOSFET is designed to minimize $R_{DS(ON)}$ yet maintain superior switching performance. This device is ideal for use in notebook battery power managements and load switches.

Applications

- Motor controls
- DC-DC converters
- Power management

Top View

Features

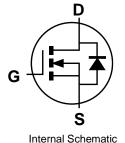
- 100% Unclamped Inductive Switching (UIS) Test in Production –
 Ensures More Reliable and Robust End Application
- High Conversion Efficiency
- Low Rds(ON) Minimizes On-State Losses
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

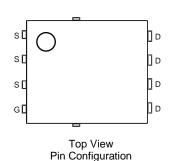
Mechanical Data

- Package: PowerDI[®]5060-8
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish—Matte Tin Annealed over Copper Leadframe;
 Solderable per MIL-STD-202, Method 208 (2)
- Weight: 0.097 grams (Approximate)









Ordering Information (Note 4)

| Part Number | Package | Packing | | |
|-------------------|-------------------------------|---------|-------------|--|
| Fait Number | Fackage | Qty. | Carrier | |
| DMTH10H4M6SPSW-13 | PowerDI5060-8 (SWP) (Type UX) | 2,500 | Tape & Reel | |

Notes:

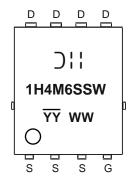
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

Pin1

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information



☐☐ = Manufacturer's Marking 1H4M6SSW = Product Type Marking Code

YYWW = Date Code Marking

YY = Last Two Digits of Year (ex: 22 = 2022) WW = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit | | |
|---|-----------------|------------------------|------------------|-----|---|
| Drain-Source Voltage | VDSS | 100 | V | | |
| Gate-Source Voltage | Vgss | ±20 | V | | |
| Continuous Dunis Compant V 40V/(Alata 5) | Steady | T _A = +25°C | - I _D | 21 | A |
| Continuous Drain Current, V _{GS} = 10V (Note 5) | State | $T_A = +100^{\circ}C$ | | 15 | |
| Continuous Drain Current Vos 101/ (Note 6) | Steady | T _C = +25°C | 1- | 115 | А |
| Continuous Drain Current, V _{GS} = 10V (Note 6) | State | $T_C = +100$ °C | ID | 81 | |
| Pulsed Drain Current (10µs Pulse, T _C = +25°C, Package | IDM | 460 | Α | | |
| Maximum Continuous Body Diode Forward Current (Note | Is | 115 | А | | |
| Pulsed Body Diode Forward Current (10µs Pulse, Tc = +2 | Ism | 460 | A | | |
| Avalanche Current (Note 7) L = 0.3mH | I _{AS} | 41 | А | | |
| Avalanche Energy (Note 7) L = 0.3mH | Eas | 252 | mJ | | |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit | |
|---|------------------------|------------------|-------------|------|
| Total Power Dissipation (Note 5) | T _A = +25°C | PD | 4.7 | W |
| Thermal Resistance, Junction to Ambient (Note 5) | | R _{0JA} | 32 | °C/W |
| Total Power Dissipation (Note 6) $T_C = +25^{\circ}C$ | | PD | 136 | W |
| Thermal Resistance, Junction to Case (Note 6) | | Rejc | 1.1 | °C/W |
| Operating and Storage Temperature Range | | TJ, TSTG | -55 to +175 | °C |

5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.

Thermal resistance from junction to soldering point (on the exposed drain pad).
 Short duration pulse test used to minimize self-heating effect.



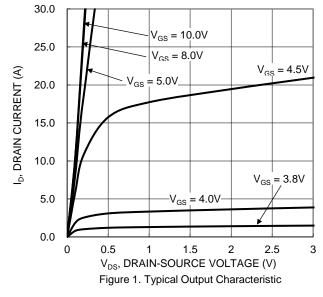
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|-----------------------------------|---------------------|-----|------|------|------|---|--|
| OFF CHARACTERISTICS (Note 7) | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 100 | _ | _ | V | VGS = 0V, ID = 10mA | |
| Zero Gate Voltage Drain Current | IDSS | _ | _ | 1 | μA | V _{DS} = 80V, V _{GS} = 0V | |
| Gate-Source Leakage | Igss | _ | _ | ±100 | nA | Vgs = ±20V, Vps = 0V | |
| ON CHARACTERISTICS (Note 7) | | | | | | | |
| Gate Threshold Voltage | Vgs(th) | 2 | | 4 | V | $V_{DS} = V_{GS}$, $I_D = 250\mu A$ | |
| Static Drain-Source On-Resistance | R _{DS(ON)} | _ | 3.1 | 4.9 | mΩ | V _{GS} = 10V, I _D = 30A | |
| Diode Forward Voltage | V _{SD} | _ | 0.8 | 1.2 | V | V _{GS} = 0V, I _S = 30A | |
| DYNAMIC CHARACTERISTICS (Note 8) | | | | | | | |
| Input Capacitance | Ciss | _ | 4327 | _ | | V _{DS} = 50V, V _{GS} = 0V f = 1MHz | |
| Output Capacitance | Coss | | 1335 | | pF | | |
| Reverse Transfer Capacitance | Crss | | 39 | | | | |
| Gate Resistance | Rg | _ | 2.1 | _ | Ω | $V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$ | |
| Total Gate Charge | Qg | _ | 66 | _ | | V _{DD} = 50V, I _D = 30A V _{GS} = 10V | |
| Gate-Source Charge | Qgs | _ | 18 | | nC | | |
| Gate-Drain Charge | Qgd | _ | 17 | _ | | | |
| Turn-On Delay Time | tD(ON) | _ | 15.2 | _ | _ | $V_{DD} = 50V, V_{GS} = 10V$ $I_{D} = 30A, R_{G} = 4.7\Omega, R_{L} = 1.1\Omega$ | |
| Turn-On Rise Time | t _R | _ | 26.4 | _ | ns | | |
| Turn-Off Delay Time | tD(OFF) | _ | 44.9 | _ | | | |
| Turn-Off Fall Time | tF | _ | 28.2 | _ | | | |
| Reverse Recovery Time | trr | _ | 63 | _ | ns | 1 00.54 41/44 4004/ | |
| Reverse Recovery Charge | Q _{RR} | | 136 | _ | nC | I _F = 22.5A, dl/dt = 100A/μs | |

Notes:

^{7.} Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing.





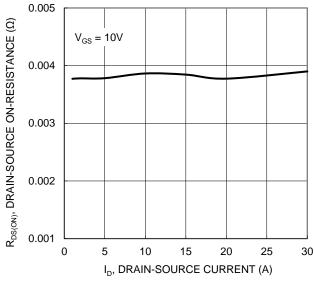


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

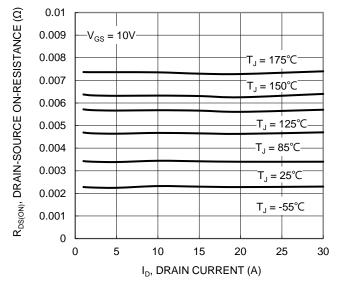
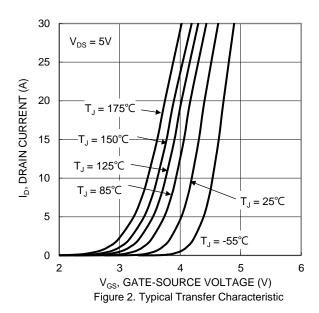
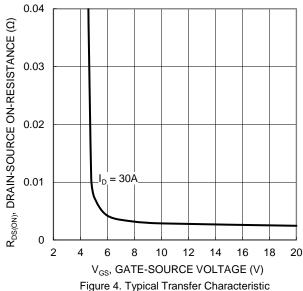


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature





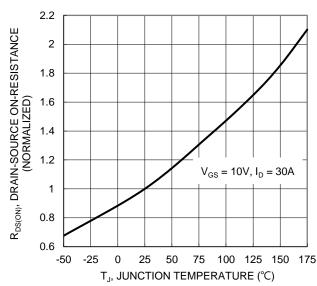


Figure 6. On-Resistance Variation with Junction Temperature



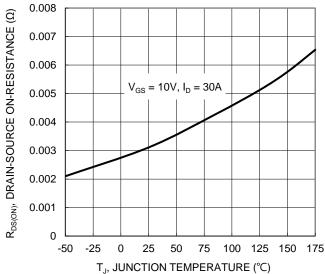


Figure 7. On-Resistance Variation with Junction Temperature

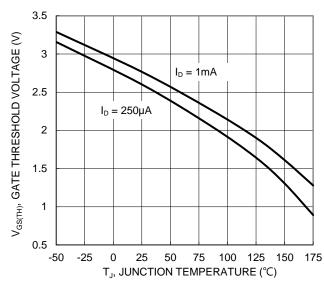


Figure 8. Gate Threshold Variation vs. Junction Temperature

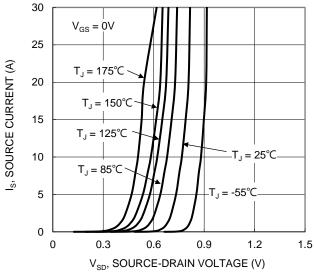


Figure 9. Diode Forward Voltage vs. Current

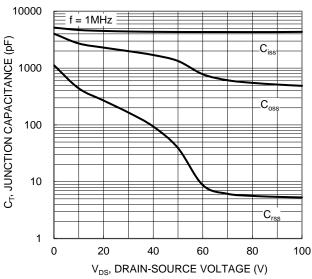


Figure 10. Typical Junction Capacitance

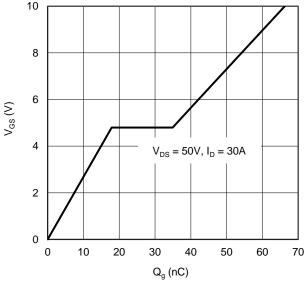


Figure 11. Gate Charge

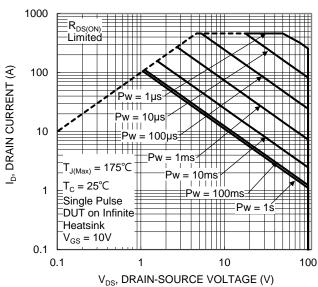


Figure 12. SOA, Safe Operation Area



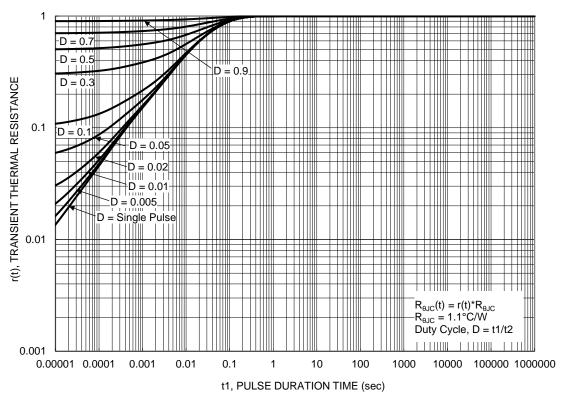


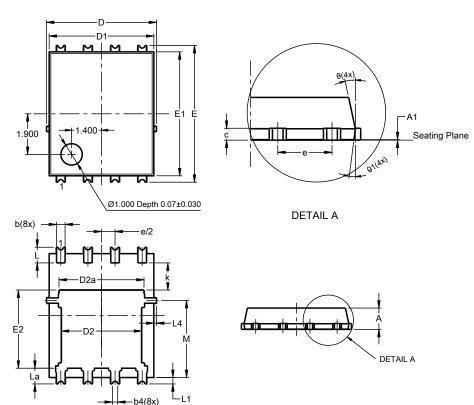
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8 (SWP) (Type UX)

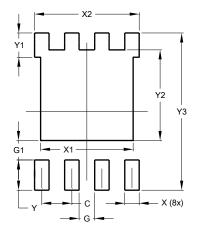


| PowerDI5060-8 (SWP) (Type UX) | | | | | |
|----------------------------------|----------|---------|-------|--|--|
| Dim | Min | Тур | | | |
| Α | 0.90 | 1.10 | 1.00 | | |
| A1 | 0 | 0.05 | | | |
| b | 0.30 | 0.50 | 0.41 | | |
| b2 | 0.20 | 0.35 | 0.25 | | |
| b4 | (|).25REF | - | | |
| С | 0.230 | 0.330 | 0.277 | | |
| D | 5 | .15 BS0 | 2 | | |
| D1 | 4.70 | 5.10 | 4.90 | | |
| D2 | 3.56 | 3.96 | 3.76 | | |
| D2a | 3.78 | 4.18 | 3.98 | | |
| Е | 6 | .40 BS0 |) | | |
| E1 | 5.60 | 6.00 | 5.80 | | |
| E2 | 3.46 | 3.86 | 3.66 | | |
| E2a | 4.195 | 4.595 | 4.395 | | |
| е | 1.27BSC | | | | |
| k | 1.05 | | | | |
| L | 0.635 | 0.835 | 0.735 | | |
| La | 0.635 | 0.835 | 0.735 | | |
| L1 | 0.200 | 0.400 | 0.300 | | |
| L1a | 0.050REF | | | | |
| L4 | 0.025 | 0.225 | 0.125 | | |
| M | 3.205 | 4.005 | 3.605 | | |
| θ | 10° | 12° | 11° | | |
| θ1 | 6° | 8° | 7° | | |
| All Dimensions in mm | | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8 (SWP) (Type UX)



| Dimensions | Value (in mm) | | |
|------------|------------------|--|--|
| С | 1.270 | | |
| G | 0.660 | | |
| G1 | 0.820 | | |
| X | 0.610 | | |
| X1 | 4.100 | | |
| X2 | 4.420 | | |
| Υ | 1.270 | | |
| Y1 | 1.020 | | |
| Y2 | 3.810 | | |
| Y3 | 6.610 | | |



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